Materials Declaration

Package	TSSOP
Body Size	4.4
LeadCount	38
Option	Pb-Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Byphenyl resin	9	5.40 E-03	45510
SiO2 Filler	85	5.10 E-02	429817
Phenol Resin	5	3.00 E-03	25283
Antimony_Sb2O3	0.5	3.00 E-04	2528
Brominated Resin	0.5	3.00 E-04	2528

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	3.53 E-02	297281
Ni	3	1.10 E-03	9271
Si	0.65	2.38 E-04	2009
Mg	0.15	5.50 E-05	464

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	1.71 E-03	14424

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	3.35 E-03	28216

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	1.49 E-03	12572

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	1.36 E-02	114369

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	4.67 E-04	3932
Ag Filler	75	1.40 E-03	11797

Molding Compound

Item	PPM	Method
Pb	Not Detected	ICP AES
Cd	Not Detected	ICP AES
Hg	Not Detected	ICP AES
Cr+6	Not Detected	DIN 53314
PBB	Not Detected	SGS In-house Method
PBDE	Not Detected	SGS In-house Method

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

Package Totals

Weight (g)	PPM
1.19 E-01	1000000

AMK-RU-D

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability t
any inaccuracy of such information.

Materials Declaration

Package	TSSOP
Body Size	4.4
LeadCount	38
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Byphenyl resin	9	5.40 E-03	45510
SiO2 Filler	85	5.10 E-02	429817
Phenol Resin	5	3.00 E-03	25283
Antimony_Sb2O3	0.5	3.00 E-04	2528
Brominated Resin	0.5	3.00 E-04	2528

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	3.53 E-02	297281
Ni	3	1.10 E-03	9271
Si	0.65	2.38 E-04	2009
Mg	0.15	5.50 E-05	464

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	1.71 E-03	14424

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	2.85 E-03	23983
Pb	15	5.03 E-04	4232

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	1.49 E-03	12572

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	1.36 E-02	114369

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	4.67 E-04	3932
Ag Filler	75	1.40 E-03	11797

Package Totals

Weight (g)	PPM
1.19 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	ICP AES
Cd	Not Detected	ICP AES
Hg	Not Detected	ICP AES
Cr+6	Not Detected	DIN 53314
PBB	Not Detected	SGS In-house Method
PBDE	Not Detected	SGS In-house Method

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

AMK-RU-A

Note: The information provided in this declaration are true to the best of ADI's knowledge
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any inaccuracy of such information.